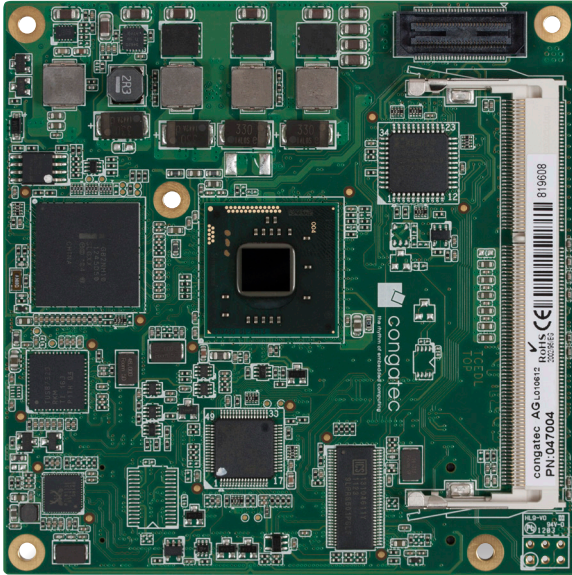


COM EXPRESS® COMPACT TYPE 6 MODULE

conga-TCA

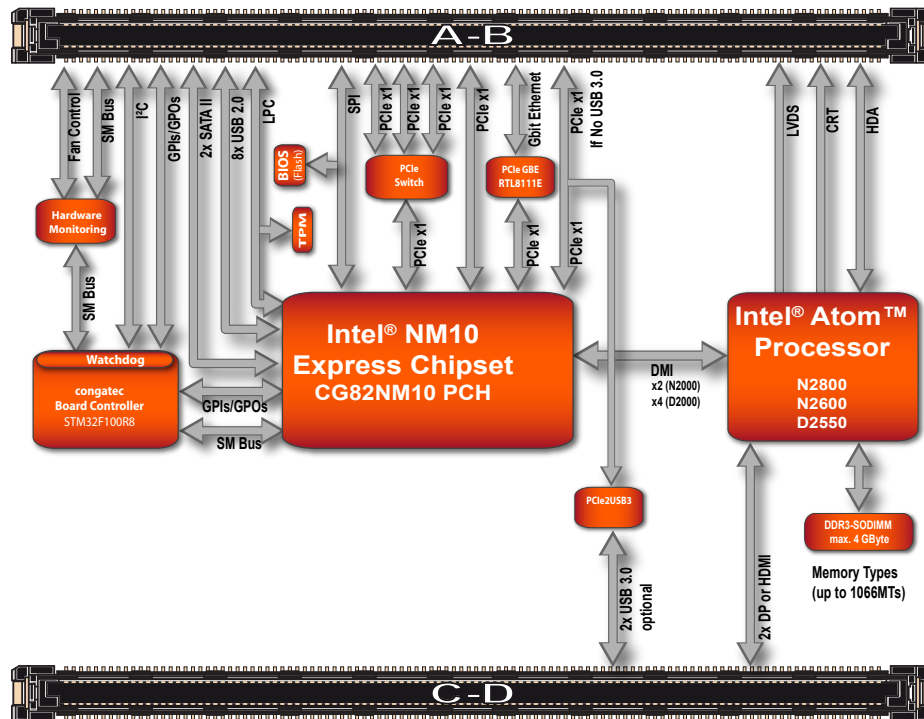


- COM Express Type 6 Entry-Level-Module
- Intel® Atom™ Dual Core Generation on 32nm
- Only 3.5 Watt TDP on Intel® Atom™ Processor N2600
- HD video performance 2D/3D
- Up to 4 GB DDR3 memory

COM  **Express®**

| | | | | | | | | | | | | | | | | |
|---------------------------------|--|--------------------|--------------------|-----------|--------------|---------|--------------------|--------------------|-----------|--------------|----------|--------------------|---------------------|-----------|--------------|----------|
| Formfactor | Formfactor COM Express™ Compact (95 x 95 mm) Type 6 Connector Layout | | | | | | | | | | | | | | | |
| CPU | Intel® Atom™ Processors <table border="1"> <tr> <td>Intel® Atom™ D2550</td> <td>1.86 GHz Dual Core</td> <td>4 threads</td> <td>L2 Cache 1MB</td> <td>10W TDP</td> </tr> <tr> <td>Intel® Atom™ N2800</td> <td>1.86 GHz Dual Core</td> <td>4 threads</td> <td>L2 Cache 1MB</td> <td>6.5W TDP</td> </tr> <tr> <td>Intel® Atom™ N2600</td> <td>1.6 GHz Single Core</td> <td>4 threads</td> <td>L2 Cache 1MB</td> <td>3.5W TDP</td> </tr> </table> | Intel® Atom™ D2550 | 1.86 GHz Dual Core | 4 threads | L2 Cache 1MB | 10W TDP | Intel® Atom™ N2800 | 1.86 GHz Dual Core | 4 threads | L2 Cache 1MB | 6.5W TDP | Intel® Atom™ N2600 | 1.6 GHz Single Core | 4 threads | L2 Cache 1MB | 3.5W TDP |
| Intel® Atom™ D2550 | 1.86 GHz Dual Core | 4 threads | L2 Cache 1MB | 10W TDP | | | | | | | | | | | | |
| Intel® Atom™ N2800 | 1.86 GHz Dual Core | 4 threads | L2 Cache 1MB | 6.5W TDP | | | | | | | | | | | | |
| Intel® Atom™ N2600 | 1.6 GHz Single Core | 4 threads | L2 Cache 1MB | 3.5W TDP | | | | | | | | | | | | |
| DRAM | 1 Socket SO-DIMM DDR3 up to 1066MT/s and 4 GByte | | | | | | | | | | | | | | | |
| Chipset | Intel® NM10 Express Chipset CG82NM10 PCH TDP 2.1W | | | | | | | | | | | | | | | |
| Ethernet | GBE Realtek 8111E | | | | | | | | | | | | | | | |
| I/O Interfaces | up to 5x PCIe 2x Serial ATA II with 3 Gb/s 8x USB 2.0 2x USB 3.0 (optional uses 1x PCIe lane) LPC bus I²C bus (fast mode 400 kHz multi-master) | | | | | | | | | | | | | | | |
| Sound | Digital High Definition Audio Interface with support for multiple audio codecs | | | | | | | | | | | | | | | |
| Graphics | Integrated Graphics supporting DirectX 9 Pixel Shader v3.0 and OGL 3.0 Two independent display pipes Support full MPEG2 (VLD/iDCT/MC) WMV Fast video Composing HW decode/acceleration for MPEG4 (AVC/H.264) & VC-1; 720p60 1080i60 1080p@24 up to 20 Mps Video Image enhancements | | | | | | | | | | | | | | | |
| LVDS | 1x24 Bit LVDS (D2550) max. Resolution 1440x900 1x18 Bit LVDS (N2000 Series) max. Resolution 1366x768 Automatic Panel Detection via EDID/EPI | | | | | | | | | | | | | | | |
| Digital Display Interface (DDI) | 2x DisplayPort 1.1 / TMDS (DVI HDMI 1.3a) | | | | | | | | | | | | | | | |
| CRT Interface | 350 MHz RAMDAC resolutions up to 1920x1200 | | | | | | | | | | | | | | | |
| congatec Board Controller | Multi Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics BIOS Setup Data Backup I²C bus (fast mode 400 kHz multi-master) Power Loss Control | | | | | | | | | | | | | | | |
| Embedded BIOS Features | AMI Aptio® UEFI 2.x firmware 4 MByte serial SPI firmware flash | | | | | | | | | | | | | | | |
| Security | Trusted Platform Module (TPM) optional. Hash and RSA algorithms key lengths up to 2,048 bits real random number generator | | | | | | | | | | | | | | | |
| Power Management | ACPI 3.0 with battery support | | | | | | | | | | | | | | | |
| Operating Systems | Microsoft® Windows 8 Microsoft® Windows 7 Linux Microsoft® Windows® embedded Standard | | | | | | | | | | | | | | | |
| Power Consumption | Typ. application: tbd. see manual for full details CMOS Battery Backup | | | | | | | | | | | | | | | |
| Temperature | Operating: 0 .. +60°C Storage: -20 .. +80°C | | | | | | | | | | | | | | | |
| Humidity | Operating: 10 - 90% r. H. non cond. Storage: 5 - 95% r. H. non cond. | | | | | | | | | | | | | | | |
| Size | 95 x 95 mm (3.74" x 3.74") | | | | | | | | | | | | | | | |

conga-TCA | Block diagram



conga-TCA | Order Information

| Article | PN | Description |
|------------------------|-------|---|
| TCA/N2600 | 47001 | COM Express Type 6 Compact module with Intel® Atom™ N2600 dual core processor with 1.6GHz, 1MB L2 cache and 800 MT/s DDR3 memory interface. |
| TCA/N2800 | 47002 | COM Express Type 6 Compact module with Intel® Atom™ N2800 dual core processor with 1.86GHz, 1MB L2 cache and 1066MT/s DDR3 memory interface. |
| TCA/D2550 | 47003 | COM Express Type 6 Compact module with Intel® Atom™ D2550 dual core processor with 1.86GHz, 1MB L2 cache and 1066MT/s DDR3 memory interface. |
| TCA/D2550 xHCI | 47004 | COM Express Type 6 Compact module with Intel® Atom™ D2550 dual core processor with 1.86GHz, 1MB L2 cache and 1066MT/s DDR3 memory interface. PCI Express to dual port USB 3.0 onboard controller. |
| TCA/HSP-T | 47032 | Standard heatspreader for COM Express modules conga-TCA and CCA. All standoffs are M2.5 thread. |
| TCA/HSP-B | 47033 | Standard heatspreader for COM Express modules conga-TCA and CCA. All standoffs are 2.7mm bore hole. |
| TCA/CSP-T-LF | 47030 | Standard passive cooling solution for COM Express modules conga-TCA and CCA with 3mm fins. All standoffs are M2.5mm thread. |
| TCA/CSP-B-LF | 47031 | Standard passive cooling solution for COM Express modules conga-TCA and CCA with 3mm fins. All standoffs are with 2.7mm bore hole. |
| TCA/CSP-T-HF | 47034 | Standard passive cooling solution for COM Express module conga-TCA and CCA with 10mm fins. All standoffs are M2.5mm thread. |
| TCA/CSP-B-HF | 47035 | Standard passive cooling solution for COM Express module conga-TCA and CCA with 10mm fins. All standoffs are 2.7mm bore hole. |
| DDR3-SODIMM-1066 (1GB) | 68750 | DDR3 SODIMM memory module with 1066MT/s and 1GB RAM. |
| DDR3-SODIMM-1066 (2GB) | 68760 | DDR3 SODIMM memory module with 1066MT/s and 2GB RAM. |
| DDR3-SODIMM-1066 (4GB) | 68765 | DDR3 SODIMM memory module with 1066MT/s and 4GB RAM. |

| Accessories | | |
|------------------------------------|--------|---|
| conga-TEVAL | 065800 | Evaluation carrier board for Type 6 COM-Express-modules |
| conga-LDVI/EPI | 011115 | LVDS to DVI converter board for digital flat panels with onboard EEPROM |
| COM-Express-carrier-board-Socket-5 | 400007 | Connector for COM-Express carrier boards height 5mm packing unit 4 pieces |
| COM-Express-carrier-board-Socket-8 | 400004 | Connector for COM-Express carrier boards height 8mm packing unit 4 pieces |

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